

RA6E2 Group

Fast Prototyping Board for RA6E2 Microcontroller
Group
FPB-RA6E2 v1
User's Manual

Renesas RA Family
RA6 Series

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1. Precaution against Electrostatic Discharge (ESD)

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2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

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5. Clock signals

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The product generates, uses, and can radiate radio frequency energy and may cause harmful interference to radio communications. There is no guarantee that interference will not occur in a particular installation. If this equipment causes harmful interference to radio or television reception, which can be determined by turning the equipment off or on, you are encouraged to try to correct the interference by one or more of the following measures:

- Ensure attached cables do not lie across the equipment.
- Reorient the receiving antenna.
- Increase the distance between the equipment and the receiver.
- Connect the equipment into an outlet on a circuit different from that which the receiver is connected.
- Power down the equipment when not in use.
- Consult the dealer or an experienced radio/TV technician for help.

Note: It is recommended that wherever possible shielded interface cables are used.

The product is potentially susceptible to certain EMC phenomena. To mitigate against them it is recommended that the following measures be undertaken:

- The user is advised that mobile phones should not be used within 10 m of the product when in use.
- The user is advised to take ESD precautions when handling the equipment.

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Renesas RA Family

FPB-RA6E2 v1
Contents

Glossary	3
1. Board Overview	4
1.1 Assumptions and Advisory Notes	6
2. Box Contents	7
3. Ordering Information	7
4. Hardware Architecture and Default Configuration	8
4.1 Board Architecture	8
4.2 System Block Diagram	8
4.3 Jumper Settings	9
4.3.1 Copper Jumpers	9
4.3.2 Traditional Pin Header Jumpers	9
4.3.3 Default Jumper Configuration	9
5. System Control and Ecosystem Access	10
5.1 Power	10
5.1.1 Power Supply Options	11
5.1.2 Power Supply Considerations	12
5.1.3 Power-up Behavior	12
5.2 Debug and Trace	12
5.2.1 On-Board Debug	12
5.2.2 Debugger Settings in e ² studio	13
5.3 Ecosystem	14
5.3.1 Digilent Pmod™ Connectors	14
5.3.2 Arduino™ Connector	16
5.4 Miscellaneous	18
5.4.1 User and Power LEDs	18
5.4.2 User and Reset Switches	19
5.4.3 MCU Boot Mode	20
5.4.4 MCU Clocks	20
6. MCU Native Pin Access	20
6.1 Breakout Pin Headers	21
6.2 MCU Current Measurement	21
7. Recommended Parts	22

8. Certifications.....	23
8.1 EMC/EMI Standards.....	23
8.2 Material Selection, Waste, Recycling and Disposal Standards	23
8.3 Safety Standards	23
9. Design and Manufacturing Information	24
10. Website and Support	24
Revision History	25

Figures

Figure 1. FPB-RA6E2 Board Top Side.....	5
Figure 2. FPB-RA6E2 Board Bottom Side.....	5
Figure 3. FPB-RA6E2 Board	7
Figure 4. FPB-RA6E2 Board Block Diagram.....	8
Figure 5. Copper Jumpers.....	9
Figure 6. Power Supply Options.....	11
Figure 7. FPB-RA6E2 Debug Interface	12
Figure 8. e ² Studio Debugger Settings	13
Figure 9. Pmod 1 Connector	15
Figure 10. Pmod 1 Solder Bridge and Trace Cut Jumpers	15
Figure 11. Pmod 2 Connector	16
Figure 12. Pmod 2 Solder Bridge and Trace Cut Jumpers	16
Figure 13. Arduino Uno Connectors.....	18
Figure 14. User LEDs	18
Figure 15. Power LED	19
Figure 16. Debug LED	19
Figure 17. Reset (S2) and User Switch (S1).....	19
Figure 18. Boot Mode Jumper (J7).....	20
Figure 19. Native Pin Access J3 and J4.....	20
Figure 20. RA +3.3 V Current Measurement Circuit.....	21
Figure 21. RA MCU +3.3 V Current Measurement Point (J9) and R94	21

Tables

Table 1. List of Abbreviations and Acronyms	3
Table 2. Kit Architecture	8
Table 3. Default Jumper Settings	9
Table 4. Debug USB Connector	12
Table 5. Debug Link Settings	13
Table 6. Pmod 1 Connector.....	14

Table 7.	Pmod 2 Connector.....	15
Table 8.	Arduino Uno Connections.....	16
Table 9.	FPB-RA6E2 Board LED Functions.....	18
Table 10.	FPB-RA6E2 Board Switches	19
Table 11.	Part Numbers.....	22
Table 12.	FPB-RA6E2 Board Design Package Contents.....	24

Glossary

Table 1. List of Abbreviations and Acronyms

BoM	Bill of Materials
ETM	Embedded Trace Module
FPB	Fast Prototyping Board
FSP	Flexible Software Package
GPIO	General Purpose Input Output
I ² C (or IIC)	Inter-Integrated Circuit
I3C	Improved Inter-Integrated Circuit
IDE	Integrated Development Environment
I/O	Input/Output
IRQ	Interrupt Request
LDO	Low Dropout
LED	Light Emitting Diode
LQFP	Low-profile Quad Flat Pack
MCU	Micro Controller Unit
MISO	Master In Slave Out
MOSI	Master Out Slave In
NC	Not Connected
Pmod™	Peripheral Module
PWM	Pulse Width Modulation
RXD	Receive Data
SCI	Serial Communications Interface
SCL	Serial Clock Line
SDA	Serial Data Line
SMD	Surface Mount Device
SPI	Serial Peripheral Interface
SRAM	Static Random Access Memory
SWD	Serial Wire Debug
TXD	Transmit Data
UART	Universal Asynchronous Receiver-Transmitter
USB	Universal Serial Bus

1. Board Overview

The FPB-RA6E2, a Fast Prototyping Board for the RA6E2 MCU Group, enables users to seamlessly evaluate the features of the RA6E2 MCU group and develop embedded systems applications using Flexible Software Package (FSP) and the e² studio IDE. Users can use on-board features along with their choice of popular ecosystems add-ons to bring their big ideas to life.

The key features of the FPB-RA6E2 board are categorized in two groups (consistent with the architecture of the board) as follows:

MCU Native Pin Access

- R7FA6E2BB3CFM MCU (referred to as RA MCU)
- 200 MHz, Arm® Cortex®-M33 core
- 256 kB Code Flash, 4 KB Data Flash, 40 kB SRAM
- 64-pin, LQFP package
- Native pin access through 2 x 32-pin male headers (not fitted)
- MCU current measurement point for precision current consumption measurement
- Multiple clock sources - Low-precision (~1%) clocks are available internal to the RA MCU. RA MCU oscillator and sub-clock oscillator crystals, providing precision 24.000 MHz (not fitted) and 32,768 Hz reference clocks are also available

System Control and Ecosystem Access

- USB Full Speed Device (micro-AB connector)
- Two 5 V input sources
 - USB (Debug, Full Speed)
 - External power supply (using 2-pin header) (not fitted)
- On-board debugger (SWD)
- User LEDs and buttons
 - Two User LEDs (green)
 - Power LED (green) indicating availability of regulated power
 - Debug/power LED (yellow) indicating power and the debug connection
 - One User button
 - One Reset button
- Two popular ecosystem expansions
 - Two Digilent Pmod™ (SPI, UART and I3C) connectors
 - Arduino™ (Uno R3) connectors
- MCU boot configuration jumper (not fitted)

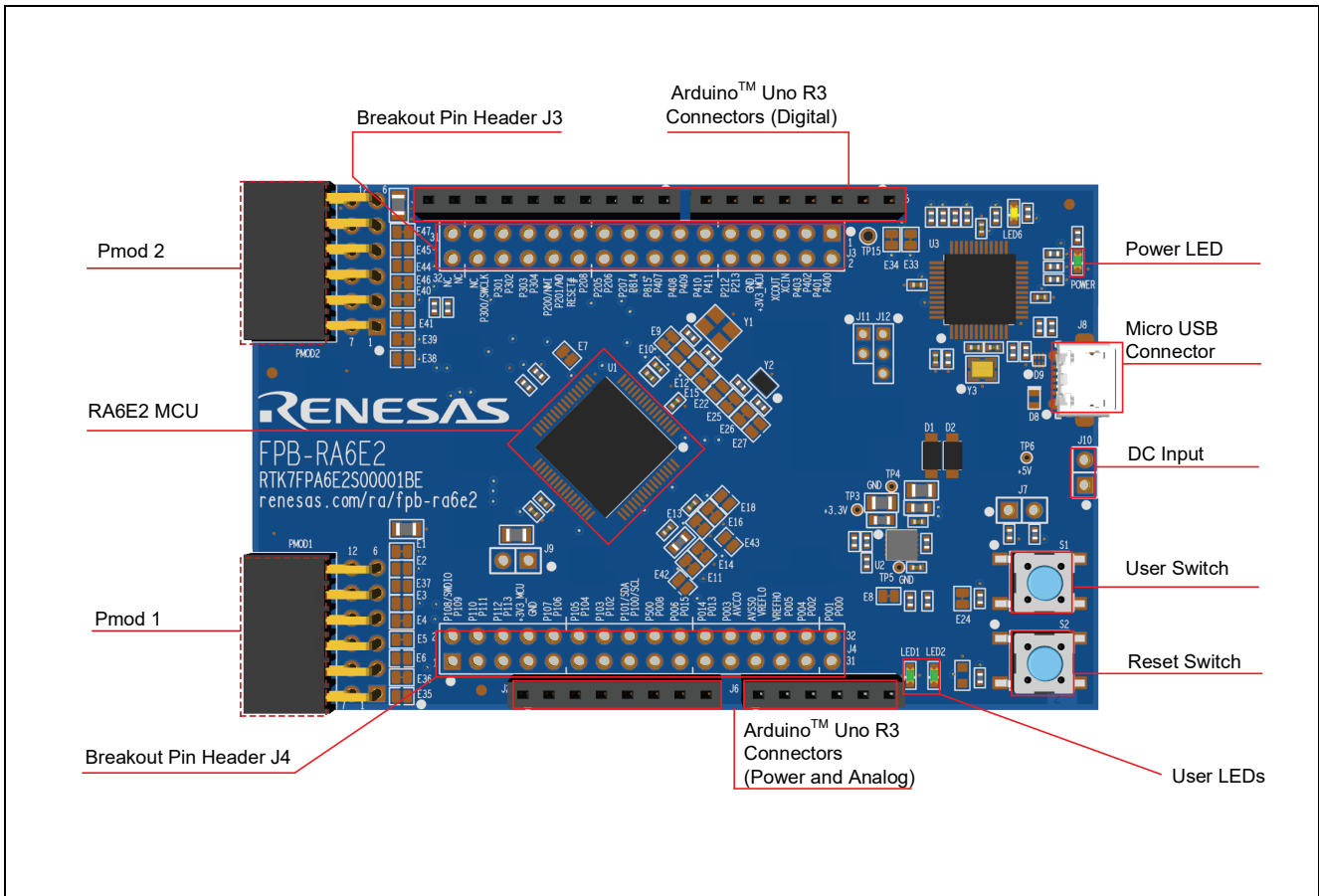


Figure 1. FPB-RA6E2 Board Top Side

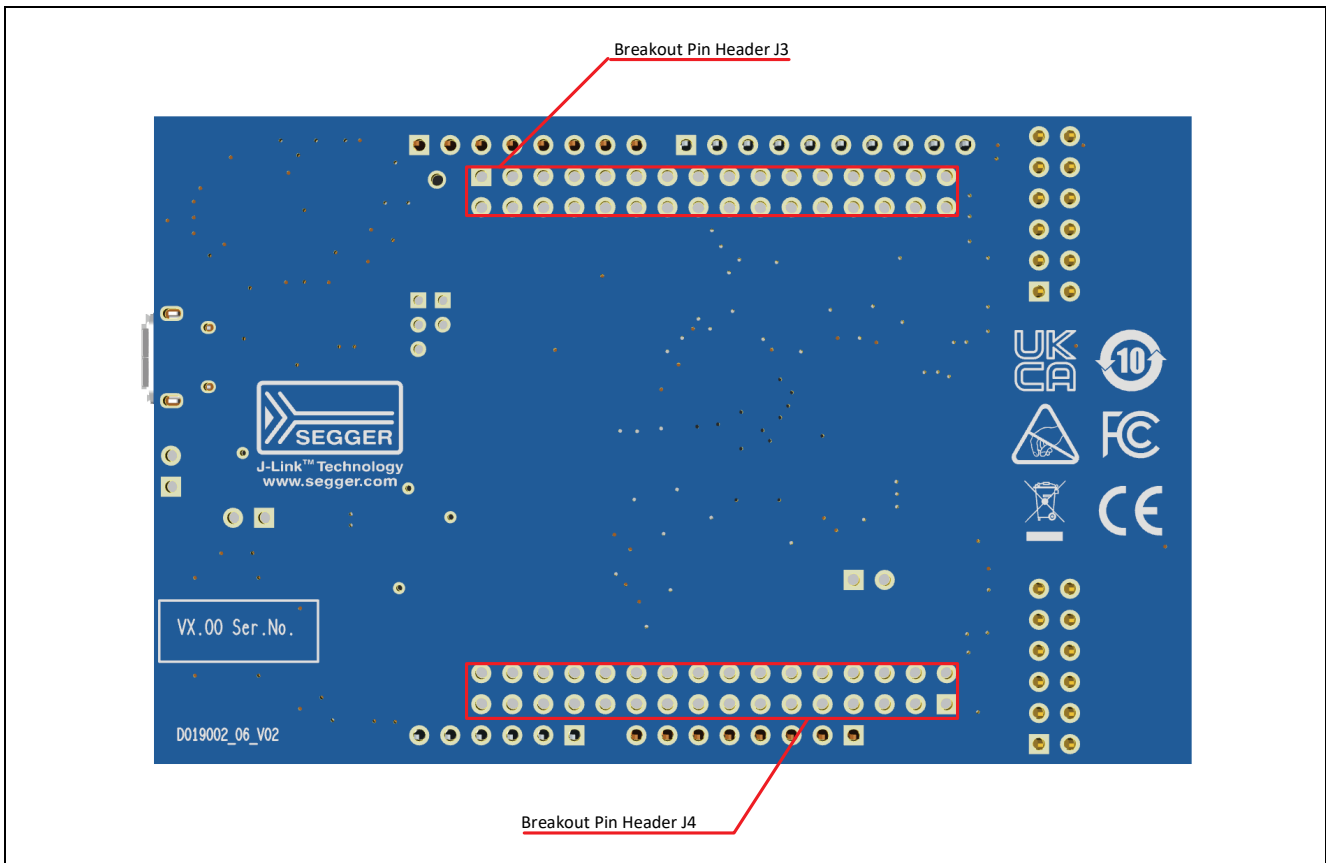


Figure 2. FPB-RA6E2 Board Bottom Side

1.1 Assumptions and Advisory Notes

1. It is assumed that the user has a basic understanding of microcontrollers and embedded systems hardware.
2. It is recommended that the user refers to the *FPB-RA6E2 Quick Start Guide* to get acquainted with the board.
3. Flexible Software Package (FSP) and Integrated Development Environment (IDE) such as e² studio are required to develop embedded applications on FPB-RA6E2 board.
4. Instructions to download and install software, import example projects, build them and program the FPB-RA6E2 board are provided in the tutorial manual.
5. The MCU fitted to the FPB-RA6E2 board may not contain the latest version of the on-chip boot firmware.

2. Box Contents

The following components are included in the box:

1. FPB-RA6E2 v1 board
2. Printed Quick Start Guide
3. China RoHS document

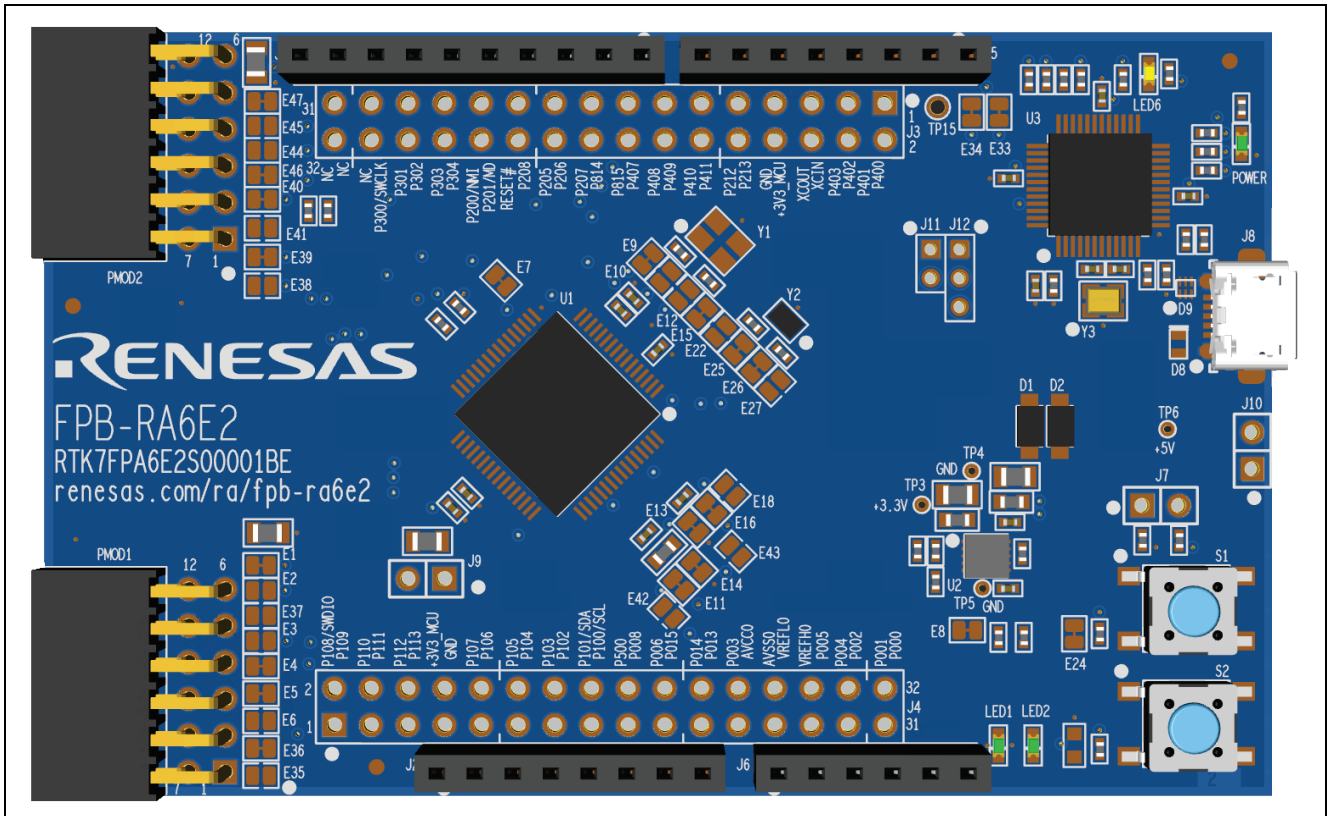


Figure 3. FPB-RA6E2 Board

3. Ordering Information

- FPB-RA6E2 v1 orderable part number: RTK7FPA6E2S00001BE

Note: The underlined character in the orderable part number represents the kit version.

- FPB-RA6E2 board dimensions: 53 mm (width) x 85 mm (length)

4. Hardware Architecture and Default Configuration

4.1 Board Architecture

The FPB-RA6E2 board is designed with an architecture similar to other boards in the FPB series. Alongside the MCU there is an on-board programmer, pin headers for access to all the pins on the MCU, a power supply regulator, some LEDs and switches, and several ecosystem I/O connectors (Pmod and Arduino).

Table 2. Kit Architecture

Board Functionality	Features	Function present on all similar boards	Functionality is:
MCU Native Pin Access	RA MCU, breakout pin headers for all MCU I/O and power, current measurement	Yes	MCU dependent
System Control and Ecosystem Access	Power, debugger, user LEDs and switches, reset switch, ecosystem connectors, boot configuration	Yes	Same or similar across other FPB boards

4.2 Block Diagram

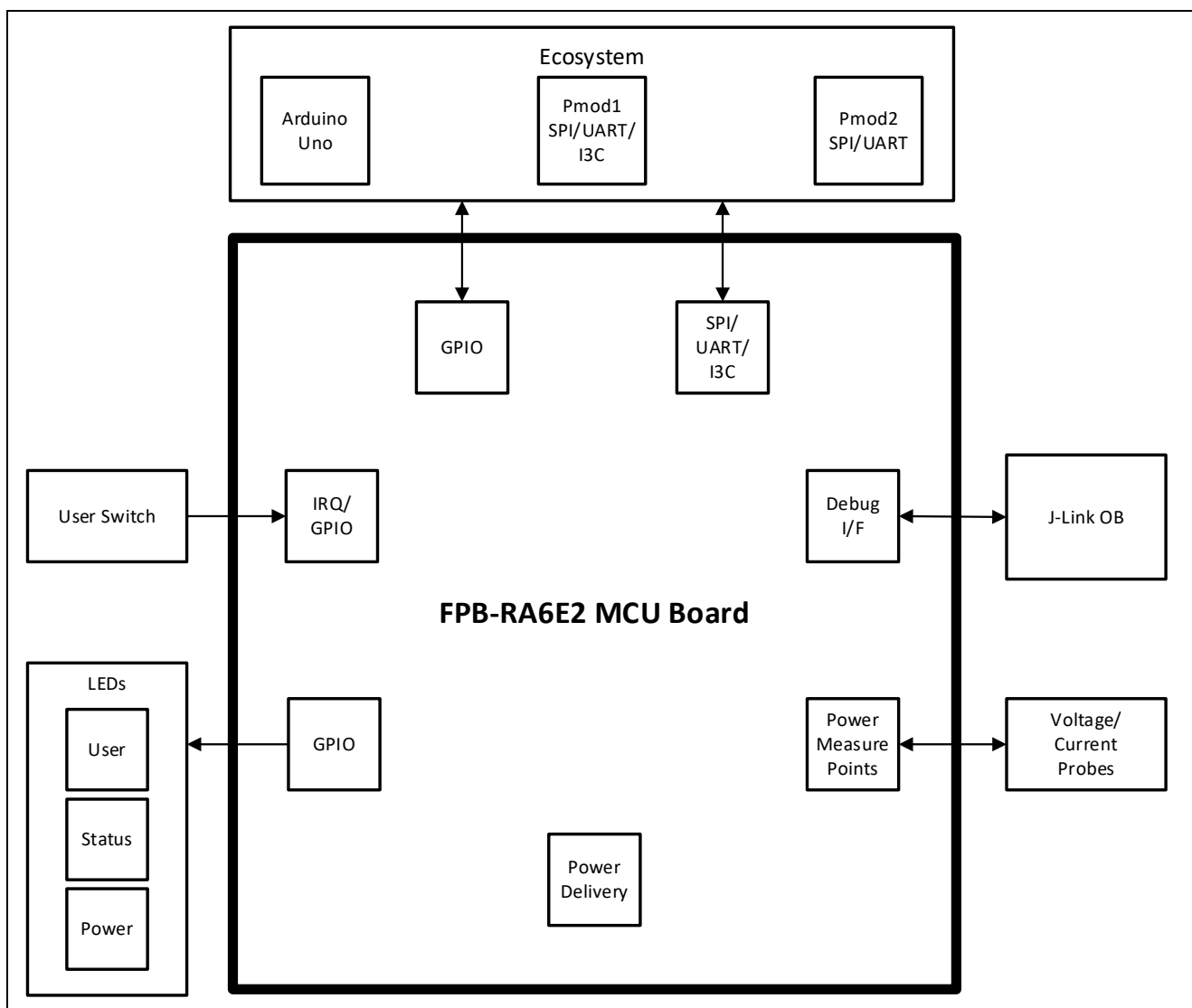


Figure 4. FPB-RA6E2 Board Block Diagram

4.3 Jumper Settings

Two types of jumpers are provided on the FPB-RA6E2 board.

1. Copper jumpers (trace-cut type and solder bridge type)
2. Traditional pin header jumpers

The following sections describe each type and their default configuration.

4.3.1 Copper Jumpers

Copper jumpers are of two types, designated **trace-cut** and **solder-bridge**.

A **trace-cut jumper** is provided with a narrow copper trace connecting its pads. The silk screen overlay printing around a trace-cut jumper is a solid box. To isolate the pads, cut the trace between pads adjacent to each pad, then remove the connecting copper foil either mechanically or with the assistance of heat. Once the etched copper trace is removed, the trace-cut jumper is turned into a solder-bridge jumper for any later changes.

A **solder-bridge** jumper is provided with two isolated pads that may be joined together by one of three methods:

- Solder may be applied to both pads to develop a bulge on each and the bulges joined by touching a soldering iron across the two pads.
- A small wire may be placed across the two pads and soldered in place.
- A SMD resistor, size 0805, 0603, or 0402, may be placed across the two pads and soldered in place. A zero-ohm resistor shorts the pads together.

For any copper jumper, the connection is considered **closed** if there is an electrical connection between the pads (default for trace-cut jumpers.) The connection is considered **open** if there is no electrical connection between the pads (default for the solder-bridge jumpers).

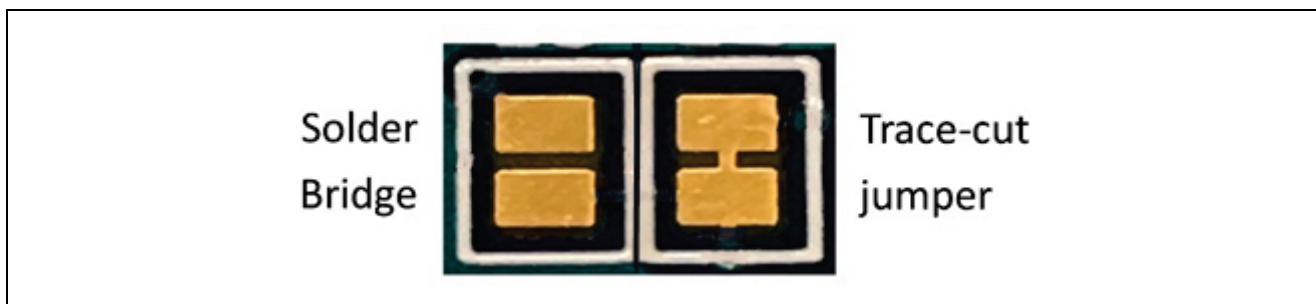


Figure 5. Copper Jumpers

4.3.2 Traditional Pin Header Jumpers

These jumpers are traditional small pitch jumpers that require an external shunt to open/close them. The traditional pin jumpers on the FPB-RA6E2 board are 0.1" (2.54 mm) pitch headers and require compatible 2.54 mm shunt jumpers.

4.3.3 Default Jumper Configuration

The following table describes the default settings for each jumper on the FPB-RA6E2 board. This includes copper jumpers (Ex designation) and traditional pin jumpers (Jx designation).

The circuit group for each jumper is the designation found in the board schematic (available in the Design Package). Functional details for many of the listed jumpers may be found in sections associated with each functional area of the kits.

Table 3. Default Jumper Settings

Location	Circuit Group	Default Open/Closed	Function
E1	Pmod1 Power	Closed	Connects +3.3 V to Pmod 1 pin 6 and pin 12
E2	Pmod1 Power	Open	Connects +5.0 V to Pmod 1 pin 6 and pin 12
E3	Pmod1 SPI	Open	Connects P111 (RSPCKA) to Pmod 1 pin 4
E4	Pmod1 I3C	Closed	Connects P101 (I3C_SDA0) to Pmod 1 pin 4

Location	Circuit Group	Default Open/Closed	Function
E5	Pmod1 I3C	Closed	Connects P100 (I3C_SCL0) to Pmod 1 pin 3
E6	Pmod1 SPI	Open	Connects P110 (MISOA/RxD9) to Pmod 1 pin 3
E7	LED2	Closed	Connects LED2 to P206
E8	LED1	Closed	Connects LED1 to P207
E9	MCU Clock	Closed	Connects J3 pin 10 to MCU pin 10 (P212/EXTAL)
E10	MCU Clock	Open	Connects 24MHz crystal to MCU pin 10 (P212/EXTAL)
E11	MCU Power	Closed	Connects AVCC0 (J4 pin 24) to +3.3 V
E12	MCU Clock	Open	Connects 24MHz crystal to MCU pin 9 (P213/XTAL)
E13	MCU Power	Closed	Connects VREFL0 (J4 pin 26) to GND
E14	MCU Power	Closed	Connects AVSS0 (J4 pin 25) to GND
E15	MCU Clock	Closed	Connects J3 pin 9 to MCU pin 9 (P213/XTAL)
E16	MCU Power	Closed	Connects VREFH0 (J4 pin 27) to +3.3 V
E18	MCU Power	Open	Connects ARDUINO_AREF to +3.3 V
E22	MCU Clock	Open	Connects J3 pin 6 to MCU pin 7 (XCOUT)
E24	Switch S1	Closed	Connects User Switch 1 to MCU P304
E25	MCU Clock	Closed	Connects 32.768KHz crystal to MCU pin 7 (XCOUT)
E26	MCU Clock	Closed	Connects 32.768KHz crystal to MCU pin 6 (XCIN)
E27	MCU Clock	Open	Connects J3 pin 5 to MCU pin 6 (XCIN)
E33	Debugger	Closed	Connects P109/TDO to Debugger P100
E34	Debugger	Closed	Connects P201/MD to P300/SWCLK
E35	Pmod1 UART	Open	Connects P303 (CTS9) to Pmod 1 pin 1
E36	Pmod1 SPI	Closed	Connects P301 (SSLA0) to Pmod 1 pin 1
E37	Pmod1 UART	Open	Connects P301 (RTS9) to Pmod 1 pin 4
E38	Pmod2 UART	Open	Connects P302 (CTS0) to Pmod 2 pin 1
E39	Pmod2 SPI	Closed	Connects P103 (SSLB0) to Pmod 2 pin 1
E40	Pmod2 SPI	Closed	Connects P102 (SCK0) to Pmod 2 pin 4
E41	Pmod2 UART	Open	Connects P103 (RTS0) to Pmod 2 pin 4
E42	MCU Power	Open	Connects AVCC0 (J4 pin 24) to MCU +3.3 V
E43	MCU Power	Open	Connects VREFH0 (J4 pin 27) to MCU +3.3 V
E44	Pmod2 UART	Open	Connects P213 (TxD0) to Pmod 2 pin 2
E45	Pmod2 UART	Open	Connects P212 (RxD0) to Pmod 2 pin 3
E46	Pmod2 UART	Closed	Connects P411 (TxD0) to Pmod 2 pin 2
E47	Pmod2 UART	Closed	Connects P410 (RxD0) to Pmod 2 pin 3
J7	MCU Boot Mode	Open	Configures the MCU for Single-chip mode
R94	MCU Power	Fitted	Connects +3.3 V to MCU. Remove when testing MCU current draw

5. System Control and Ecosystem Access

The FPB-RA6E2 provides a power supply regulator, an on-board debugger, simple I/O (switches and LEDs), and popular I/O ecosystem connectors. These are all described in detail below.

5.1 Power

The FPB-RA6E2 board is designed for +5 V operation. An on-board Low Dropout (LDO) regulator is used to convert the 5 V supply to a 3.3 V supply. The 3.3 V supply is used to power the RA MCU and other peripheral features.

5.1.1 Power Supply Options

This section describes the different ways in which FPB-RA6E2 board can be powered.

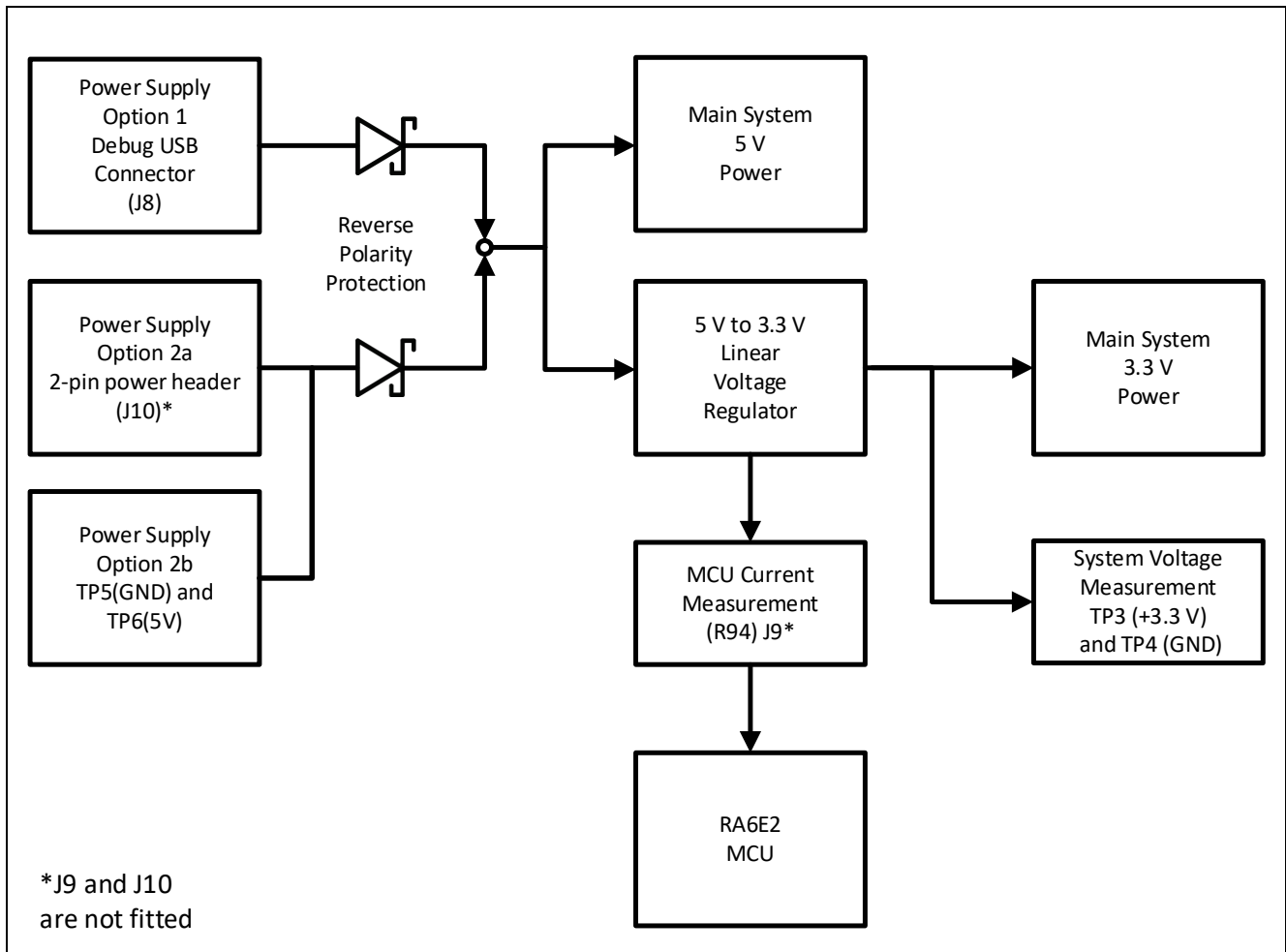


Figure 6. Power Supply Options

The MCU can be operated at a lower voltage than 3.3 V by removing the current measurement resistor and powering the MCU via TP3.

Note: Other changes to the circuit where interfaces or pull-up resistors are used may also need to be removed. Please review the schematic carefully before making these changes.

5.1.1.1 Option 1: Debug USB

5 V may be supplied from an external USB host to the USB debug connector (J8). Power from this source is connected to the main system 5 V power. Reverse current protection is provided between this connector and the main system 5 V power.

5.1.1.2 Option 2: Header Connector J10

5 V may be supplied from an external power supply to test points on the board. TP6 (5 V) and TP5 (GND) are loop-style test points, and J10 provides large via style test points that can accommodate a 0.1" (2.54 mm) pin header or connector. The two types of test points are electrically equivalent, and both are provided for user convenience. Power from this source is connected to the main system 5 V power. Reverse current protection is provided between the 5 V test points and the main system 5 V power.

5.1.2 Power Supply Considerations

The on-board LDO regulator which supplies +3.3 V has a built-in current limit of 2.0 A. Make sure the total current required by the RA MCU, any active on-board features, and any connected peripheral devices does not exceed this limit.

Note: The total current available from a typical USB host is 100 mA before enumeration, and 500 mA maximum. Depending on the configuration of the kit, multiple power sources may be required.

5.1.3 Power-up Behavior

When powered, the green LED next to the POWER legend will illuminate. The yellow DEBUG LED will also illuminate.

5.2 Debug and Trace

The FPB-RA6E2 board can be programmed and debugged using the built-in SEGGER J-Link Emulator On-Board debugger.

5.2.1 On-Board Debug

The on-board debug functionality is provided using Renesas RA4M2 Debug MCU and SEGGER J-Link® firmware.

Debug USB Micro-B connector (J8) connects the RA4M2 Debug MCU to an external USB full speed host, allowing re-programming and debugging of the target RA MCU firmware. This connection is the default debug mode for the FPB-RA6E2 board.

The RA4M2 Debug MCU connects to the target RA MCU using the SWD interface.

Table 4. Debug USB Connector

Debug USB Connector		FPB-RA6E2
Pin	Description	Signal/Bus
J8-1	+5VDC	+5V_USB_DBG
J8-2	Data-	USB_JLOB_DM (U3 pin 14)
J8-3	Data+	USB_JLOB_DP (U3 pin 15)
J8-4	USB ID, jack internal switch, cable inserted	NC
J8-5	Ground	GND

A yellow indicator(LED6), DEBUG LED, shows the visual status of the debug interface. When the FPB-RA6E2 board is powered on, and the DEBUG LED is blinking, it indicates that the RA4M2 Debug MCU is not connected to a programming host. When the DEBUG LED is on solid, it indicates that it is connected to a programming interface. When the DEBUG LED is flickering, it indicates that data is being transferred between the RA4M2 Debug MCU and the programming host.

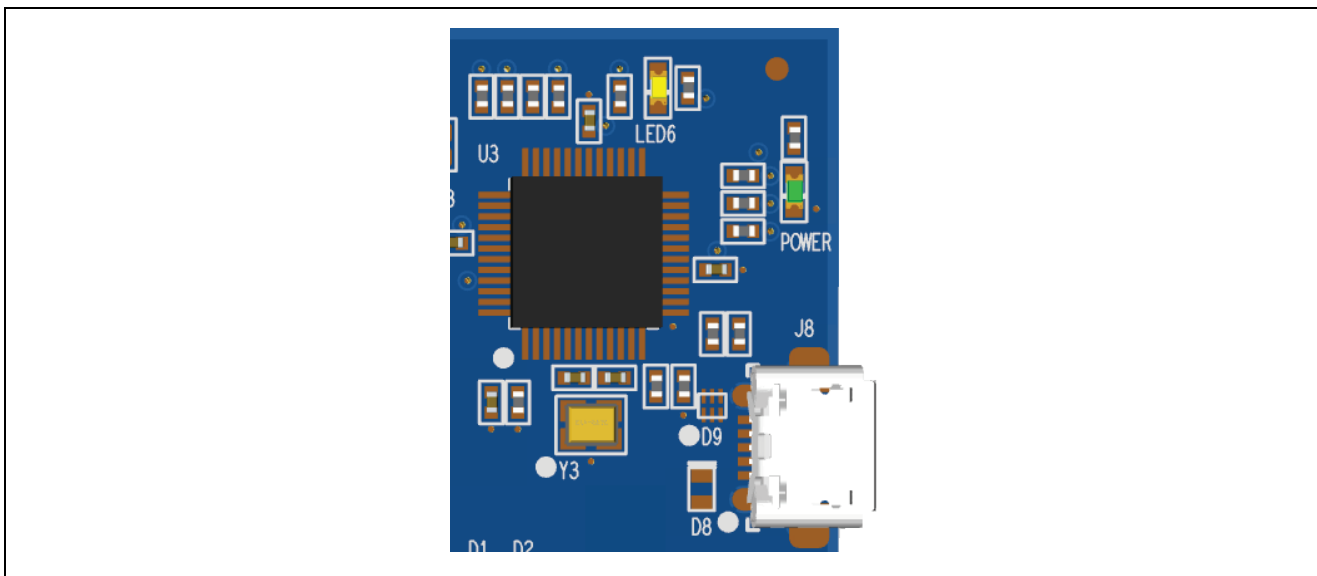


Figure 7. FPB-RA6E2 Debug Interface

5.2.1.1 Debugger Link Settings

Table 5. Debug Link Settings

Link	Setting	Function
E34	Closed	Normal debugger operation
	Open	P201/MD and P300/SWCLK are not connected

5.2.2 Debugger Settings in e² studio

Figure 8 shows the settings for e² studio when creating a new project for the FPB-RA6E2 Fast Prototyping Board.

[Debug hardware]: Select [J-Link (ARM)]

[Target Device]: Select [R7FA6E2BB]

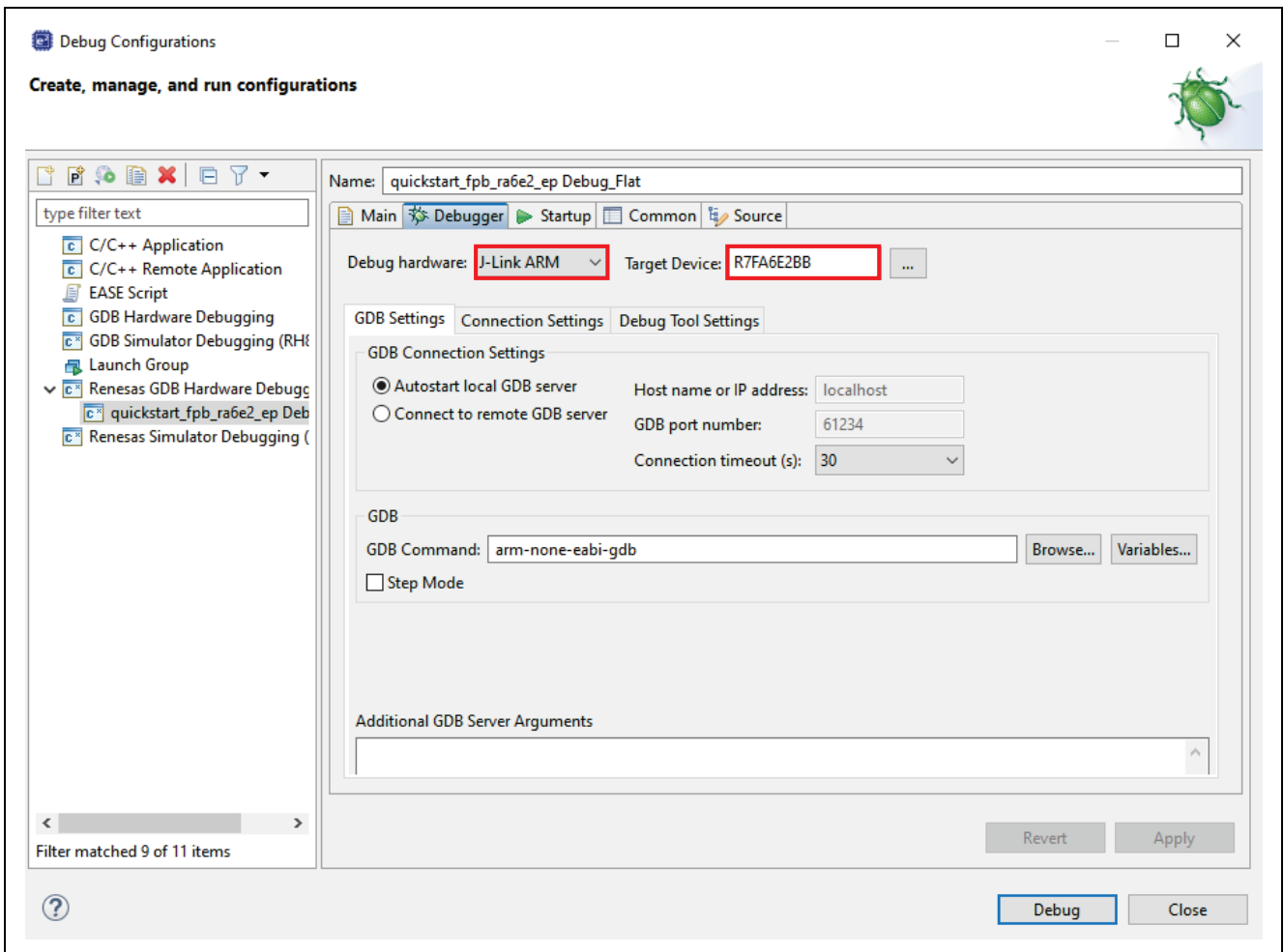


Figure 8. e² Studio Debugger Settings

5.3 Ecosystem

The Ecosystem connectors provide users the option to simultaneously connect several third-party add-on modules compatible with two popular ecosystems using the following connectors:

1. Two Digilent Pmod™ (SPI ,UART and I3C) connectors
2. Arduino™ (Uno R3) connectors

5.3.1 Digilent Pmod™ Connectors

Two 12-pin connectors are provided to support Pmod modules where the RA MCU acts as the master, and the connected module acts as a slave device.

These interfaces may be configured in firmware to support several Pmod types such as Type-2A (expanded SPI) and Type-3A (expanded UART).

The FPB-RA6E2 board also provides jumpers so the 12-pin connector may alternatively be used for Pmod Type-6A (I3C).

The default 12-pin Pmod interface supports +3.3 V devices. Please ensure that any Pmod device installed is compatible with a +3.3 V supply*.

The Pmod interface may also support +5.0 V devices.

*Please ensure that only 5 V modules with 3V3 interface signals are used when this option is selected.

Note that both Pmods use the SCI peripheral in “Simple SPI” mode, and so do not offer the full functionality of the SPI peripheral. Please see the hardware manual for full details of the SCI “Simple SPI” mode.

5.3.1.1 Pmod 1

A 12-pin right angle connector is fitted at Pmod1. The connections support Pmod Type-2A (expanded SPI) and Type-3A (expanded UART) and Type-6A (I3C). The RA MCU acts as the I3C master, and the connected module acts as an I3C slave device. This interface may additionally be re-configured in firmware as several other Pmod types.

Table 6. Pmod 1 Connector

Pmod1 Connector Default				FPB-RA6E2	Pmod 1 Configuration	
Pin	Option Type 2A / 3A	Option Type 3A	Option Type 6A	Signal/Bus	Short	Open
PMOD1-1	SS / CTS			P301 (SSLA0/CTS9)	E36	E35, E37
		CTS		P303 (CST9)	E35	E36
PMOD1-2	MOSI / TXD	TXD		P109 (MOSIA/TXD9)		
PMOD1-3	MISO / RXD	RXD		P110 (MISOA/RXD9)	E6	E5
			SCL	P100 (SCL0)	E5	E6
PMOD1-4	SCK			P111 (RSPCKA)	E3	E4, E37
		RTS		P301 (RTS9)	E37	E3, E4, E36
			SDA	P101 (SDA0)	E4	E3, E37
PMOD1-5	GND			GND		
PMOD1-6	VCC			+3.3 V*	E1	E2
				+5.0 V*	E2	E1
PMOD1-7	GPIO			P402 (IRQ4)		
PMOD1-8	GPIO / RESET			P005 (RESET)		
PMOD1-9	GPIO			P107 (GPIO/SSLA2)		
PMOD1-10	GPIO			P106 (GPIO)		
PMOD1-11	GND			GND		
PMOD1-12	VCC			+3.3 V*	E1	E2
				+5.0 V*	E2	E1

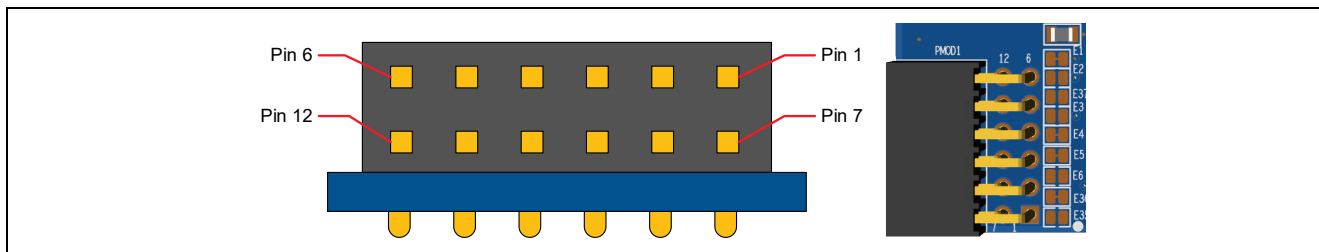


Figure 9. Pmod 1 Connector

Note: Exercise caution while modifying power source trace jumpers, E1 and E2. Permanent damage to the FPB-RA6E2 board and/or connected modules may result.

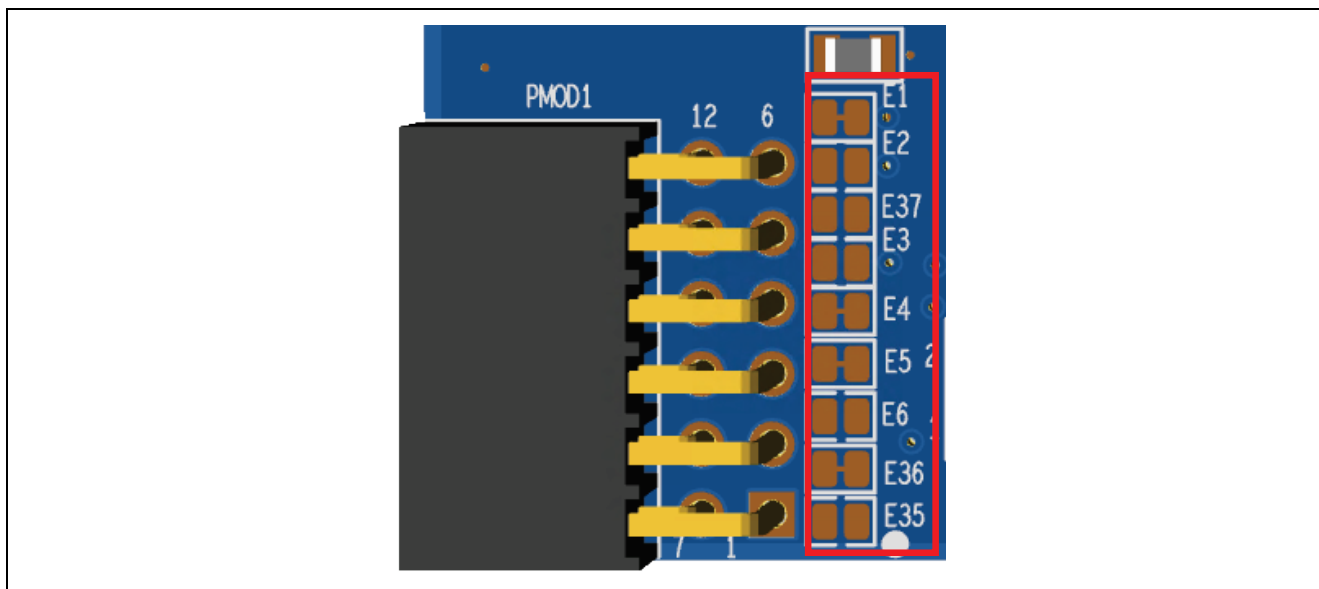


Figure 10. Pmod 1 Solder Bridge and Trace Cut Jumpers

5.3.1.2 Pmod 2

A 12-pin right angle connector is fitted at Pmod 2. The RA MCU acts as the SPI master, and the connected module acts as an SPI slave device. This interface may additionally be re-configured in firmware as several other Pmod types.

This Pmod interface supports +3.3 V devices. Please ensure that any Pmod device installed is compatible with a +3.3 V supply.

Note: P212 and P213 are shared with the external crystal. If an external crystal is used these pins will be unavailable.

Table 7. Pmod 2 Connector

Pmod 2 Connector				FPB-RA6E2	Pmod 2 Configuration		External clock Configuration	
Pin	Option Type 2A / 3A	Option Type 3A	Option Type 3A	Signal/Bus	Short	Open	Short	Open
PMD2-1	SS / CTS			P103 (SS0/CTS0)	E39	E38		
		CTS	CTS	P302 (CTS0)	E38	E39		
PMD2-2	MOSI / TXD	TXD		P411 (MOSI0/TXD0)	E46	E44		
			TXD	P213 (TXD0)	E44	E46	E15	E12
PMD2-3	MISO / RXD	RXD		P410 (MISO0/RXD0)	E47	E45		
			RXD	P212 (RXD0)	E45	E47	E9	E10
PMD2-4	SCK			P102 (SCK0)	E40	E41		
		RTS	RTS	P103 (RTS0)	E41	E40, E39		
PMD2-5	GND			GND				

Pmod 2 Connector				FPB-RA6E2	Pmod 2 Configuration	External clock Configuration	
PMOD2-6	VCC			+3.3 V			
PMOD2-7	GPIO			P205 (IRQ1)			
PMOD2-8	GPIO / RESET			P407 (RESET)			
PMOD2-9	GPIO			P015			
PMOD2-10	GPIO			P014			
PMOD2-11	GND			GND			
PMOD2-12	VCC			+3.3 V			

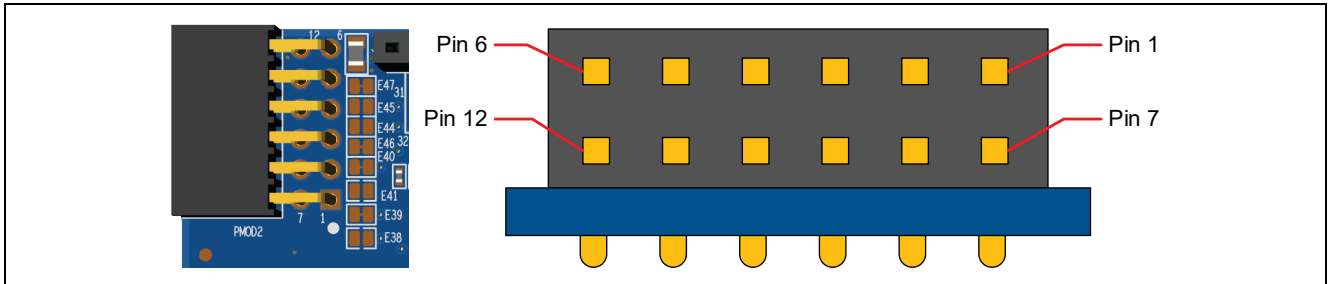


Figure 11. Pmod 2 Connector

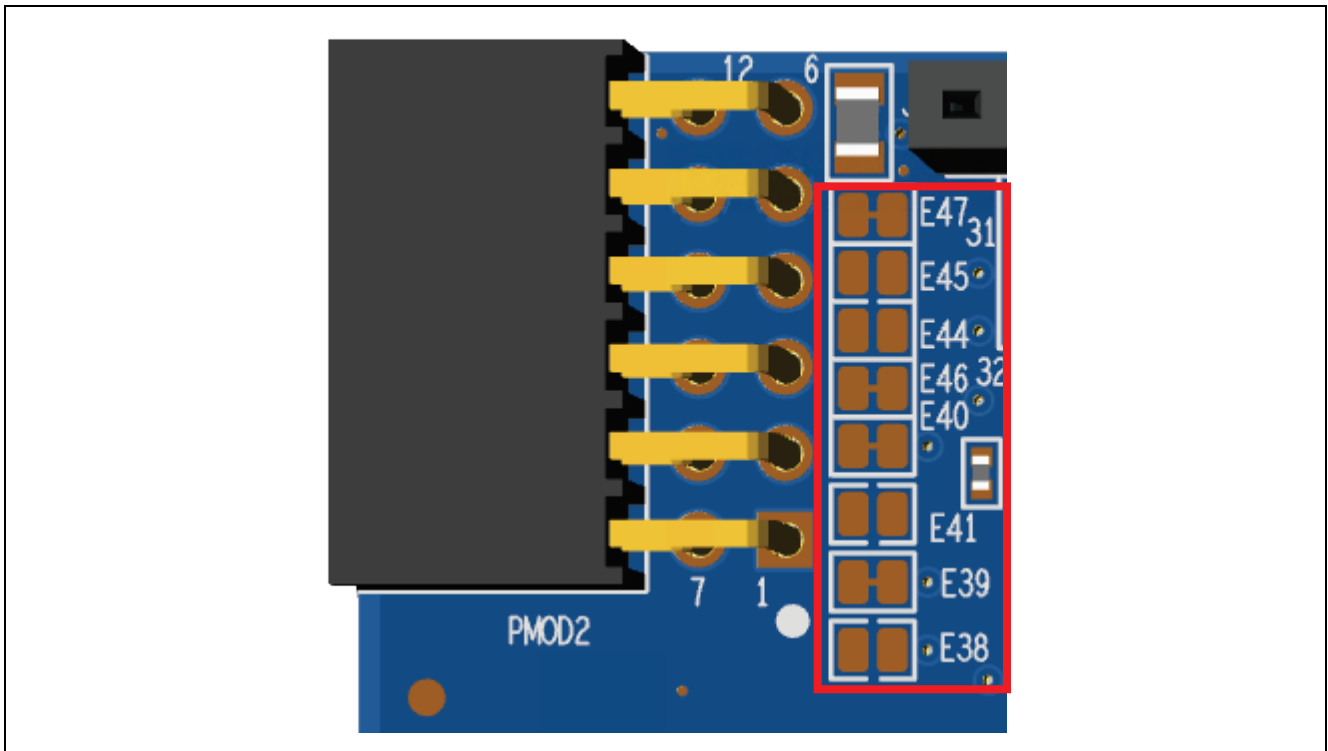


Figure 12. Pmod 2 Solder Bridge and Trace Cut Jumpers

5.3.2 Arduino™ Connector

An Arduino Uno R3 compatible connector interface is provided.

Table 8. Arduino Uno Connections

Arduino Compatible Connector		FPB-RA6E2
Pin	Description	Signal/Bus
J2-1	NC	NC
J2-2	IOREF	+3.3 V
J2-3	RESET	P208

Arduino Compatible Connector		FPB-RA6E2
Pin	Description	Signal/Bus
J2-4	3.3 V	+3.3 V
J2-5	5 V	+5 V
J2-6	GND	GND
J2-7	GND	GND
J2-8	VIN	NC
J6-1	A0	P000 (AN000)
J6-2	A1	P001 (AN001)
J6-3	A2	P002 (AN002)
J6-4	A3	P004 (AN004)
J6-5	A4	P003 (AN007)
J6-6	A5	P013 (AN011)
J5-1	D0 / RXD	P410 (GPIO/RXD0)
J5-2	D1 / TXD	P411 (GPIO/TXD0)
J5-3	D2 / INT0	P105 (GPIO/IRQ0)
J5-4	D3 / INT1 / PWM	P408 (GPIO/IRQ7/GTIOC1B)
J5-5	D4	P500 (GPIO)
J5-6	D5 / PWM	P409 (GPIO/GTIOC1A)
J5-7	D6 / PWM	P113 (GPIO/GTIOC2A)
J5-8	D7	P008 (GPIO)
J1-1	D8	P006 (GPIO)
J1-2	D9 / PWM	P403 (GPIO/GTIOC3A)
J1-3	D10 / SS / PWM	P301 (GPIO/SSLA0/GTIOC4B)
J1-4	D11 / MOSI / PWM	P109 (GPIO/MOSIAGTIOC1A)
J1-5	D12 / MISO / PWM	P110 (GPIO/MISOA/GTIOC1B)
J1-6	D13 / SCK	P111 (GPIO/RSPCKA)
J1-7	GND	GND
J1-8	AREF	ARDUINO/VREFH0
J1-9	I3C_SDA	P101 (I3C_SDA0)
J1-10	I3C_SCL	P100 (I3C_SCL0)

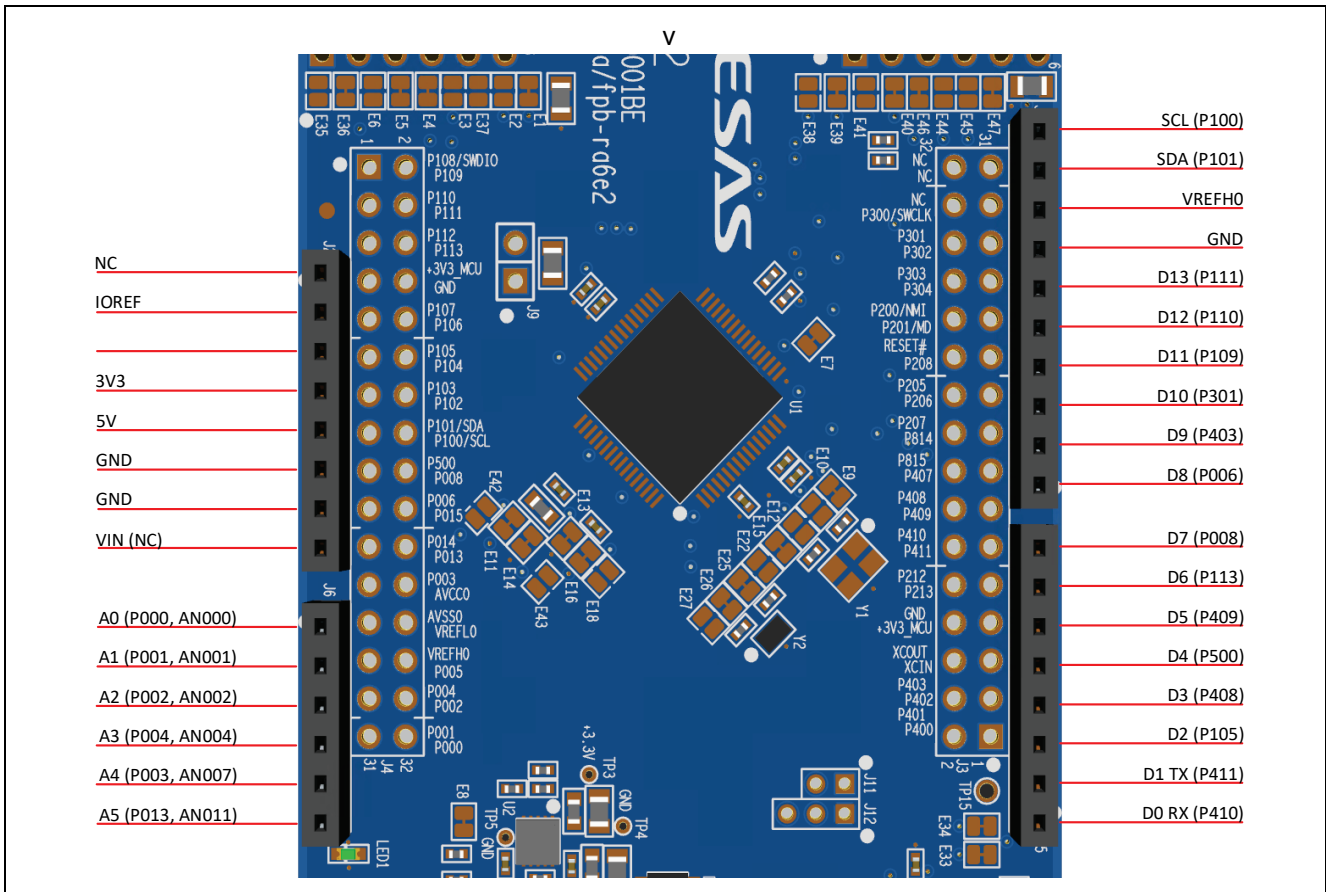


Figure 13. Arduino Uno Connectors

5.4 Miscellaneous

5.4.1 User and Power LEDs

Four LEDs are provided on the FPB-RA6E2 board.

Behavior of the LEDs on the FPB-RA6E2 board is described in the following table.

Table 9. FPB-RA6E2 Board LED Functions

Designator	Color	Function	MCU Control Port
LED1	Green	User LED	P207
LED2	Green	User LED	P206
POWER	Green	Power on indicator	+3.3 V
LED6	Yellow	Debug LED	Renesas RA4M2 Debug MCU

The User LEDs may be isolated from the main MCU so that the associated ports can be used for other purposes. To disconnect LED1 from P207, trace cut jumper E8 must be open. To disconnect LED2 from P206, trace cut jumper E7 must be open.

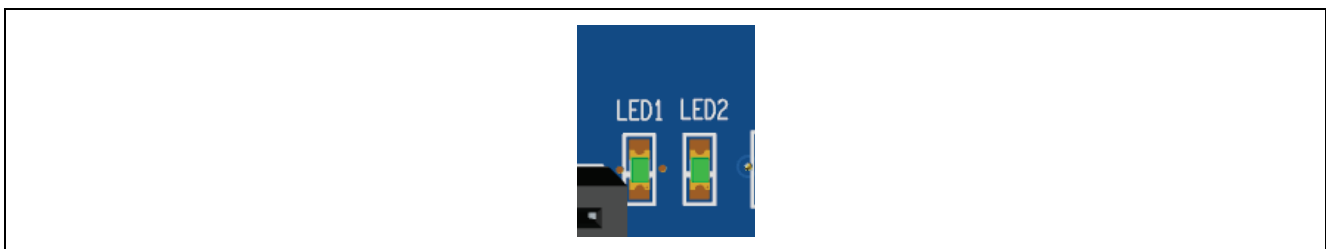


Figure 14. User LEDs

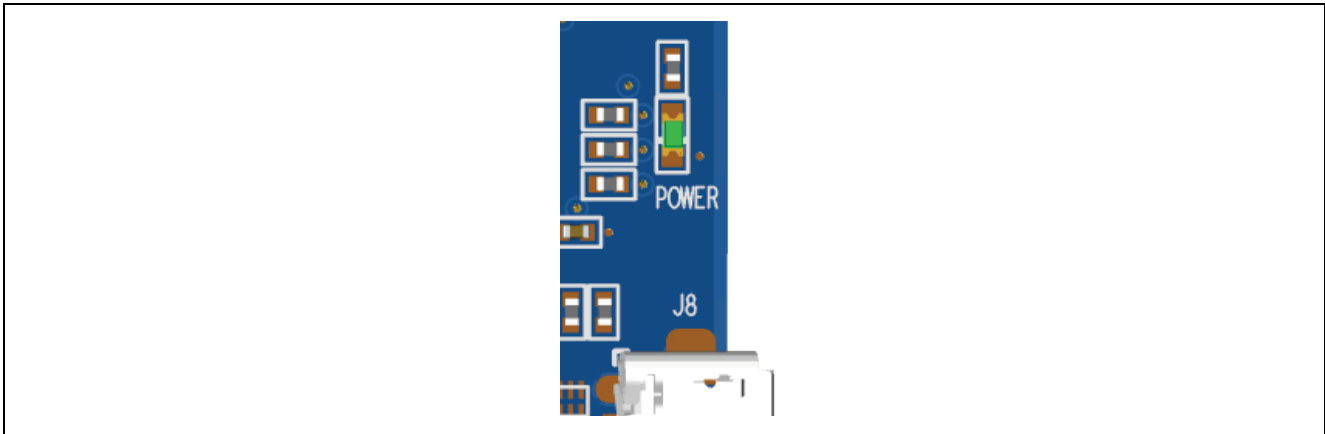


Figure 15. Power LED

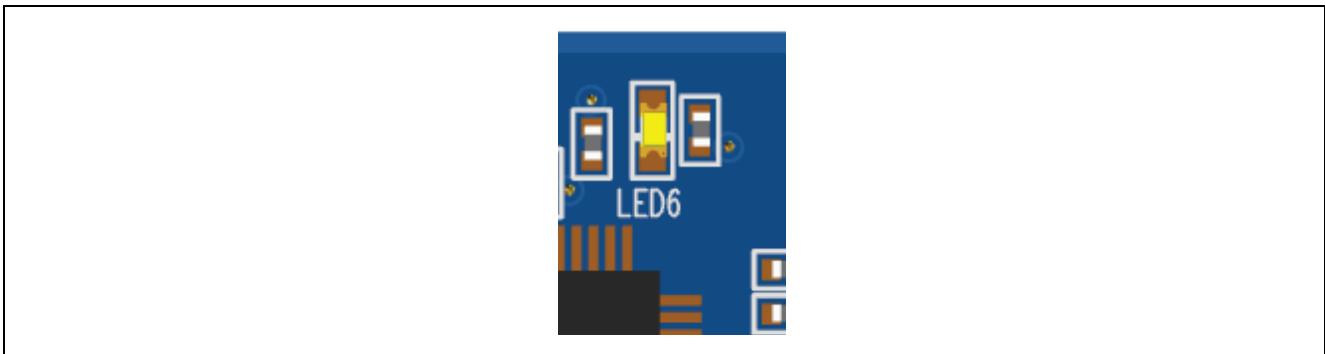


Figure 16. Debug LED

5.4.2 User and Reset Switches

Two miniature, momentary, mechanical push-button type SMD switches are mounted on the FPB-RA6E2 board.

Pressing the reset switch (S2) generates a reset signal to restart the RA MCU.

Table 10. FPB-RA6E2 Board Switches

Designator	Function	MCU Control Port
S1	User Switch	P304 (IRQ9)
S2	MCU Reset Switch	RESET#

The User Switch S1 may be isolated from the MCU, so that the associated port can be used for other purposes. To disconnect S1 from P304, trace cut jumper E24 must be open.

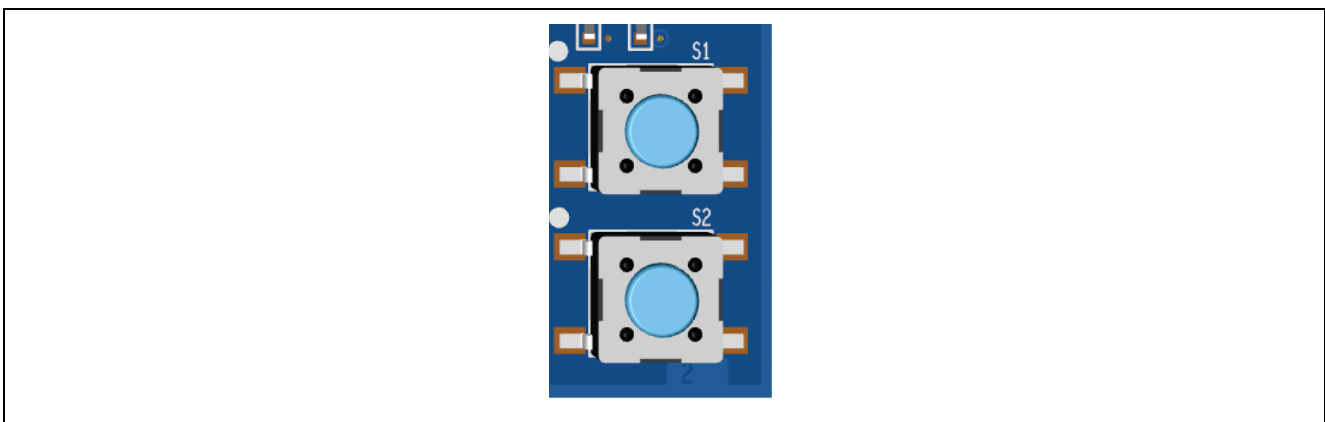


Figure 17. Reset (S2) and User Switch (S1)

5.4.3 MCU Boot Mode

A two-pin header (J7) can be fitted to select the boot mode (P201) of the RA MCU. For normal operation (single-chip mode), leave J7 open. To enable SCI boot mode, place a jumper on J7.

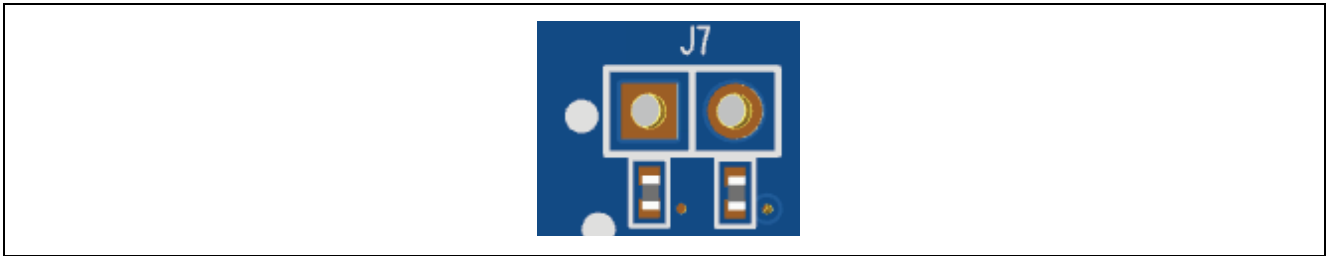


Figure 18. Boot Mode Jumper (J7)

5.4.4 MCU Clocks

The board is fitted with a RA MCU sub-clock oscillator crystal, providing a precision 32,768 Hz reference clock. The option has also been provided to fit an RA MCU oscillator crystal, providing a precision 24.000 MHz reference clock. A recommended part is the Diodes Incorporated FL2400022.

6. MCU Native Pin Access

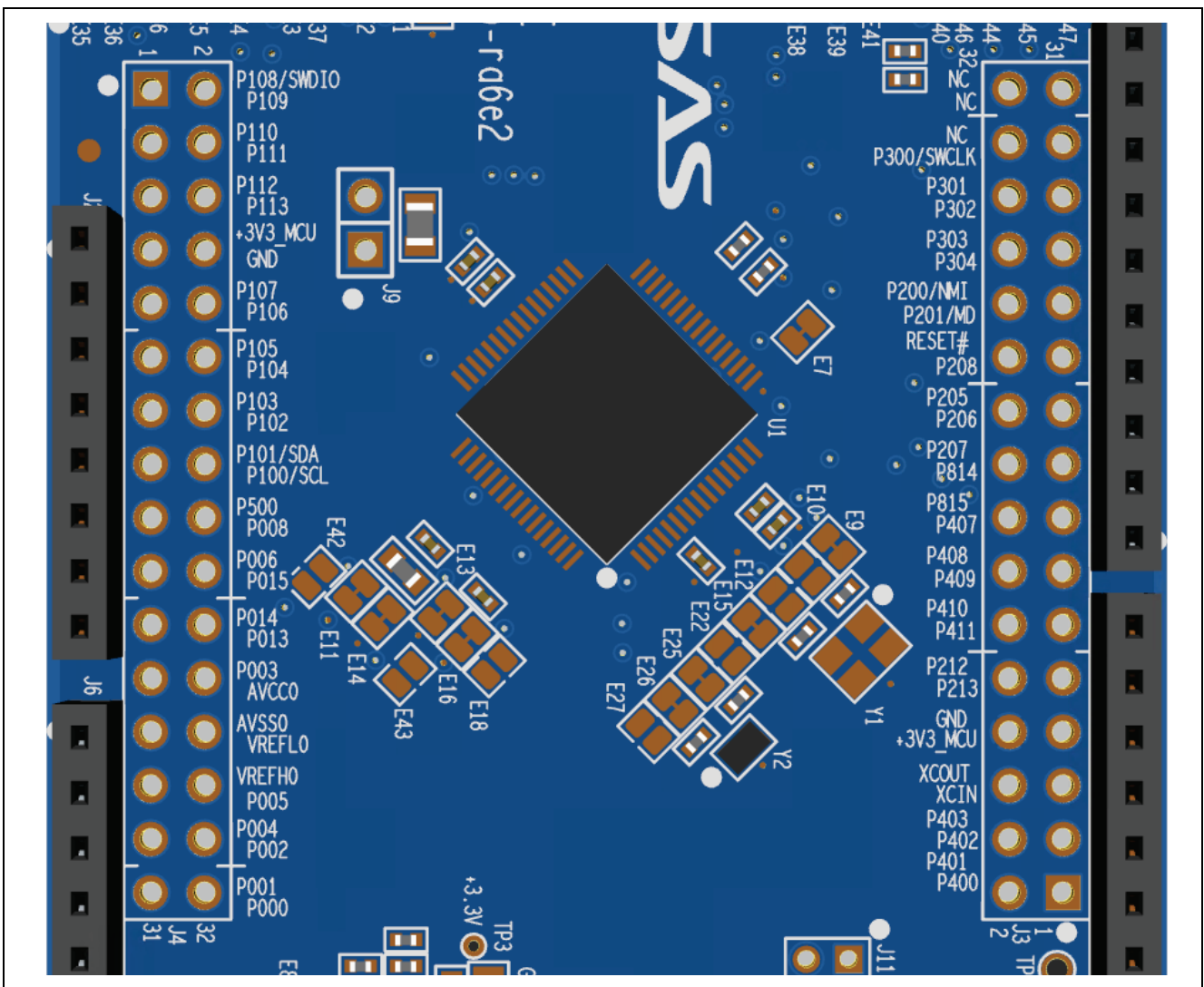


Figure 19. Native Pin Access J3 and J4

6.1 Breakout Pin Headers

The FPB-RA6E2 board pin headers (not fitted), J3 and J4, provide access to all RA MCU interface signals, and to voltages for all RA MCU power ports. Each header pin is labelled with the voltage or port connected to that pin. Refer to the RA6E2 MCU Group User's Manual for details of each port function, and the FPB-RA6E2 board schematic for pin header port assignments.

The placement of the breakout pin headers allows for a standard 2.54 mm (0.100") center breadboard to be placed on both pin headers simultaneously. This can be used for prototyping and testing of custom circuitry for use with the RA6E2 MCU.

6.2 MCU Current Measurement

Included near the RA MCU is resistor R94 and test connector J9 (not fitted) to measure the MCU core current.

Resistor R94 is 0 Ω (SMD 0805) as supplied. It should be removed in order to measure the current consumption using an ammeter connected between J9 pins 1 and 2.

Alternatively, it could be removed and replaced with a suitable low value resistor (such as 100 mΩ), and then a voltmeter used to measure the voltage between J9 pins 1 and 2. The current drawn by the MCU can then be calculated using Ohm's Law.

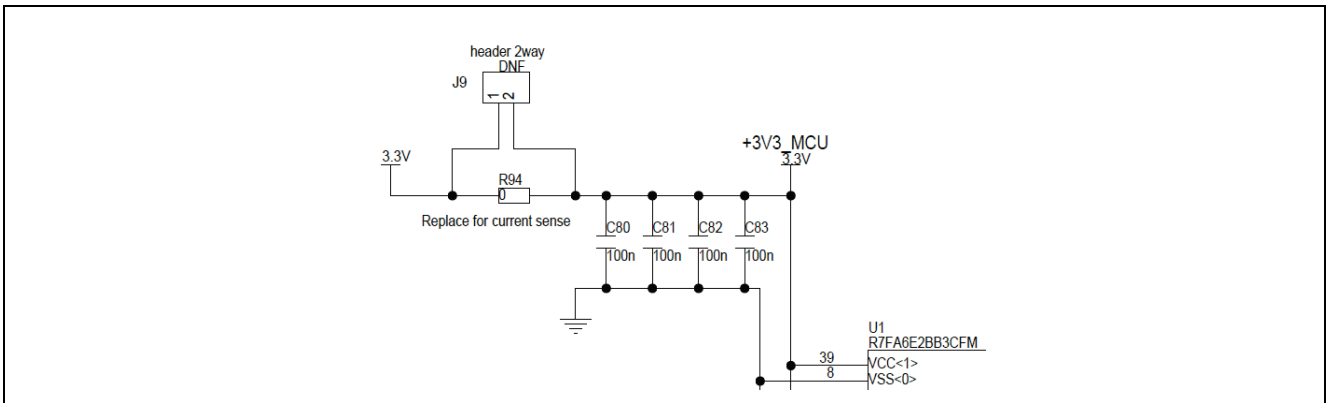


Figure 20. RA +3.3 V Current Measurement Circuit

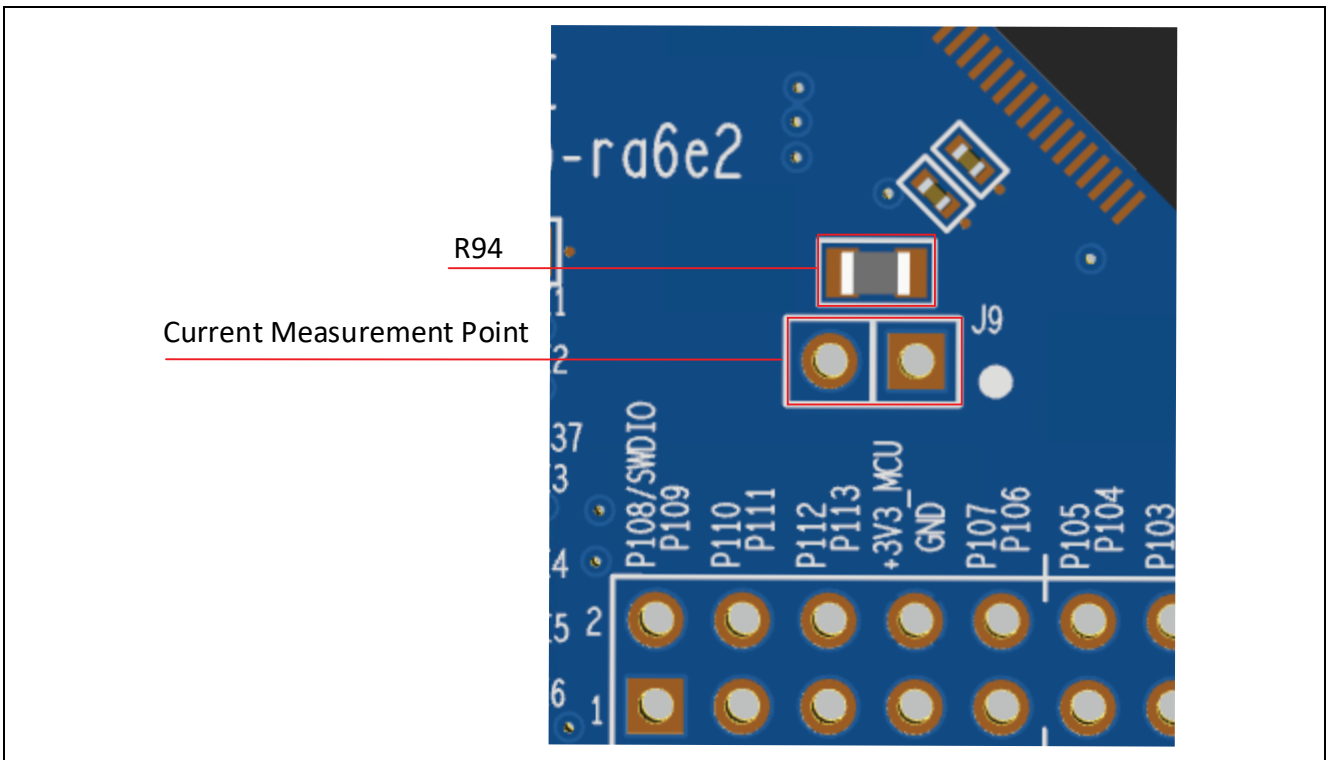


Figure 21. RA MCU +3.3 V Current Measurement Point (J9) and R94

7. Recommended Parts

Table 11 lists recommended part numbers for optional components that can be fitted as required.

Table 11. Part Numbers

Designator(s)	Description	Manufacturer	Part Number
Y1	24 MHz Crystal	Diodes Incorporated	FL2400022
J3, J4	50-way male header	Würth Elektronik	613 032 211 21
J7, J9, J10	2-way male header	Würth Elektronik	613 002 111 21

8. Certifications

The FPB-RA6E2 v1 board meets the following certifications/standards. See page 4 of this user's manual for the disclaimer and precautions.

8.1 EMC/EMI Standards

- FCC Notice (Class A)



This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

NOTE- This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/television technician for help.

- Innovation, Science and Economic Development Canada ICES-003 Compliance:

CAN ICES-3 (A)/NMB-3(A)

- CE Class A (EMC)



This product is herewith confirmed to comply with the requirements set out in the Council Directives on the Approximation of the laws of the Member States relating to Electromagnetic Compatibility Directive 2014/30/EU.

Warning – This is a Class A product. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures to correct this interference.

- UKCA Class A (EMC)



This product is in conformity with the following relevant UK Statutory Instrument(s) (and its amendments): 2016 No. 1091 Electromagnetic Compatibility Regulations 2016.

Warning – This is a Class A product. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures to correct this interference.

- Taiwan: Chinese National Standard 13438, C6357 compliance, Class A limits
- Australia/New Zealand AS/NZS CISPR 32:2015, Class A

8.2 Material Selection, Waste, Recycling and Disposal Standards

- EU RoHS
- China SJ/T 113642014, 10-year environmental protection use period.

8.3 Safety Standards

- UL 94V-0

9. Design and Manufacturing Information

The design and manufacturing information for the FPB-RA6E2 v1 kit is available in the “FPB-RA6E2 v1 Design Package” available on renesas.com/ra/fpb-ra6e2.

- Design package file name: fpb-ra6e2-v1-designpackage.zip
- Design package contents

Table 12. FPB-RA6E2 Board Design Package Contents

File Type	Content	File/Folder Name
File (PDF)	Schematics	fpb-ra6e2-v1-schematics
File (PDF)	Mechanical Drawing	fpb-ra6e2-v1-mechdwg
File (PDF)	3D Drawing	fpb-ra6e2-v1-3d
File (PDF)	BoM	fpb-ra6e2-v1-bom
Folder	Manufacturing Files	Manufacturing Files
Folder	Design Files	Design Files-Cadence Allegro

10. Website and Support

Visit the following URLs to learn about the kit and the RA family of microcontrollers, download tools and documentation, and get support.

FPB-RA6E2 Resources	renesas.com/ra/fpb-ra6e2
RA Product Information	renesas.com/ra
RA Product Support Forum	renesas.com/ra/forum
RA Videos	renesas.com/ra/videos
RA Kit Feedback and Feature Request	renesas.com/ra/kitfeedback
Renesas Support	renesas.com/support

Provide Feedback/Request a Feature

Renesas aims to provide the best microcontroller kit experience to help our customers jumpstart innovation and take products to market faster with the RA family of microcontrollers. The Renesas RA microcontroller kits have been designed with a lot of attention to detail and customer-centered thinking in every aspect of the design. Renesas aims to exceed customer expectation.

Renesas looks forward to hearing your feedback and learning how we can enhance your experience. Please share your feedback at renesas.com/ra/kitfeedback.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jun.29.23	—	Initial release

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Publication Date: Jun.29.23

Published by: Renesas Electronics Corporation

FPB-RA6E2 v1 – User's Manual

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